



**PATENT**

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

**In re Application of:**

Richard W. Wensel

**Serial No.:** 10/600,149

**Filed:** June 19, 2003

**For:** SEMICONDUCTOR DIE WITH  
ATTACHED HEAT SINK AND  
TRANSFER MOLD

**Confirmation No.:** 6258

**Examiner:** N. Ha

**Group Art Unit:** 2814

**Attorney Docket No.:** 2269-3061.8US  
(96-0893.07/US)

**Notice of Allowance Mailed:**

November 4, 2004

**NOTICE OF EXPRESS MAILING**

Express Mail Mailing Label Number: EL994825043US

Date of Deposit with USPS: February 3, 2005

Person making Deposit: Steven P. Wong

**AMENDMENT PURSUANT TO 37 C.F.R. § 1.312(a)**

Mail Stop ISSUE FEE  
Commissioner for Patents  
P.O. Box 1450  
Alexandria, Virginia 22313-1450

Sir:

Please amend the above-referenced application as follows:

**Serial No. 10/600,149**

**Amendments to the Specification** begin on page 3 of this paper.

**Amendments to the Claims** are reflected in the listing of claims which begins on page 5 of this paper.

**Remarks** begin on page 8 of this paper.